



HIGH PRECISION DICING BLADE UV TAPE AND SOLUTION SUPPLIER

MADE IN CHINA

WINTIME SEMICONDUCTOR

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COMPANY INTRODUCTION

Core Business



Precision dicing blade



UV tape



Dicing scheme



Dressing board

- 2007** • Launched DZR soft blade.
- 2009** • Launched JS (metal) and SZ (resin) soft blades.
- 2015** • Launched a domestic series of UV dicing tapes.
- 2016** • Launched DZY high-precision wafer dicing blade.
- 2017** • Launched the industry's narrowest kerf-width dicing blade (10-15 μm).
- 2020** • Launched the Established operations in Rugao (Nantong) and completed construction of the Nantong factory. narrowest kerf-width dicing blade (10-15 μm).
- 2021** • Completed development of an ultra-thin (9 μm) dicing blade and began supplying it to customers in volume.
- 2022** • It was recognized as a National High-tech Enterprise and received orders and recognition from many leading domestic and international customers. In the same year, it completed its Series A financing round, led by Yida Capital, with follow-on investments from Zhonggao Fund, Hefei Industrial Investment, etc., with a valuation of 270 million yuan.
- 2023** • We have established a deep cooperation with the Department of Materials at Fudan University, introduced cutting-edge talents, and invested over 100 million yuan to start the construction of a new factory area.
- 2024** • The annual revenue has been doubling for four consecutive years. The new factory was officially put into use that year, with a production capacity of over 1 million pieces, making it one of the most advanced and largest scribing blade production bases in the country. Weiteng scribing blades have embarked on a new journey.
- 2025** • Through the public announcement and recognition of "Provincial Specialized, Refined, Unique and Innovative", it was awarded the "Annual Technology Breakthrough Award" at the China IC Industry Awards. The series of products are widely applied in fields such as wafers, LED chips, ultrasonic probes, integrated circuit packaging materials, and optical communication devices.

Factory Overview

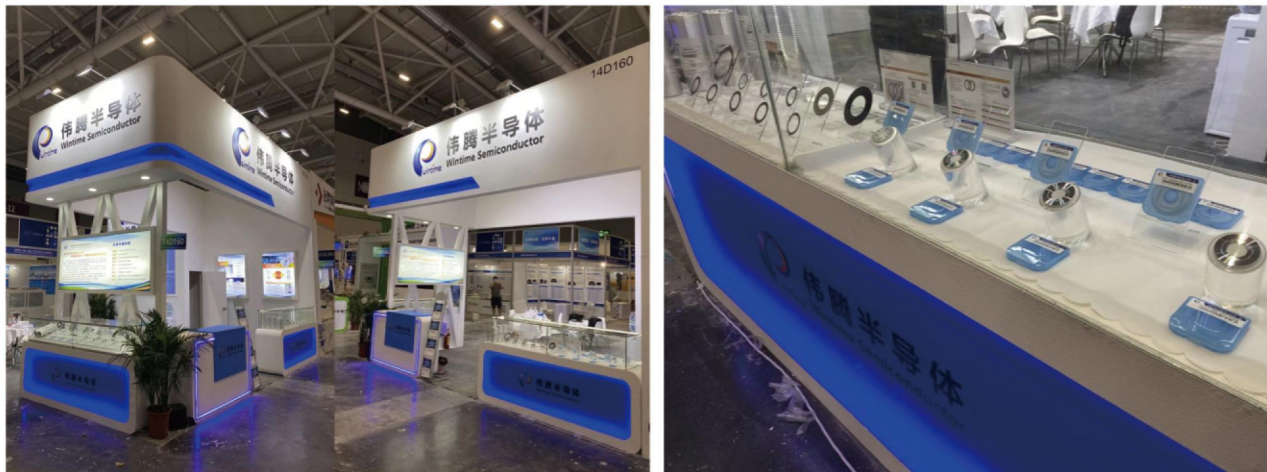
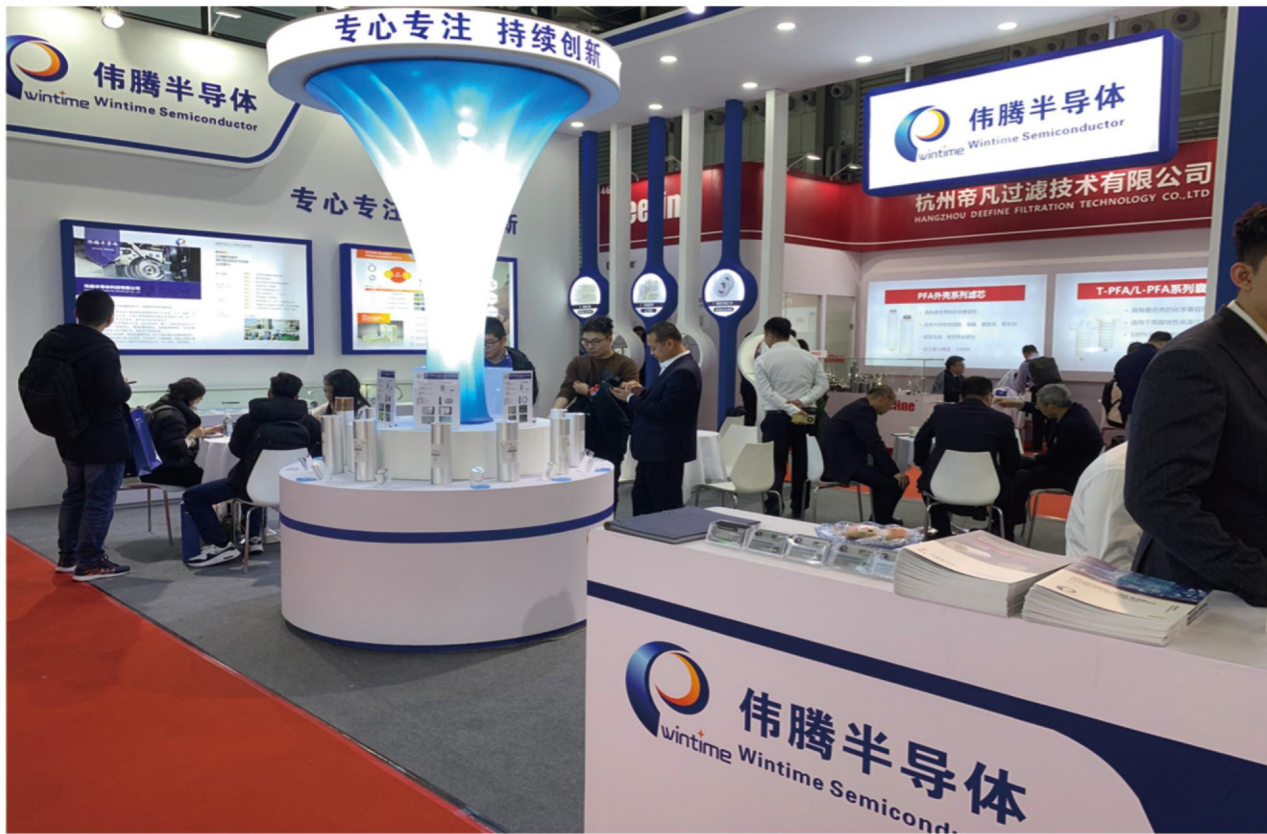


COOPERATIVE PARTNER





EXHIBITIONS OVER THE YEARS



DICING BLADES

Electroformed Soft Blade



Electroformed Hard Blade



Electroformed Blade

Precision Cutting Blade

Sintered Blade

Metal Bond Blade



Resin Bond Blade



Applications of Precision Cutting Blades

Blade Types	Blade Cutting Application Fields	
Electroformed Hard Blade	Silicon materials such as semiconductor wafers	
Electroformed Soft Blade	LED packaging materials, piezoelectric ceramics, and related materials	
Metal Blade	IC packaging materials, ceramic materials, etc.	
Resin Blade	IC packaging materials, ultra-hard materials such as glass, etc.	



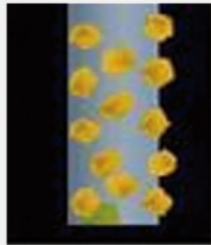

DICING BLADE INTRODUCTION

DZR Dicing Blade

The DZR dicing blade is composed of metallic nickel and diamond abrasive, featuring ultra-thin structure and excellent cutting performance. It is suitable for grooving and dicing a variety of hard and brittle non-metallic materials, such as semiconductor wafers, functional ceramics, alloy materials, and semiconductor packaging materials.



Code Notes

L1	L2
 <p>L1 dicing blade features high strength, suitable for grooving and dicing with narrow kerf widths.</p>	 <p>L2 dicing blade has consistent diamond exposure height on both sides, which reduces chipping and kerf angle deviation during cutting. Applicable for thicknesses above 0.04 mm.</p>

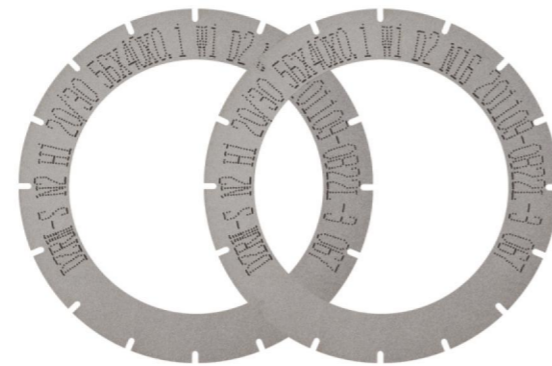
Example: DZRL2N2 H22/454X40X0.05

DZR: Model Name	H : Bond Hardness						
L: Type	H1 Soft Bond H2 Standard Hardness Bond						
N: Diamond Abrasive Concentration	2/4: Diamond Grit Size						
N1 Low Concentration	N2 Standard Concentration	N3 High Concentration					
Serial Number	2/4	2/6	4/6	4/8	10/20	20/30	30/40
Grit Number	4000#	3000#	2000#	1700#	800#	600#	400#

54: Outer Diameter 40: Inner Diameter 0.05: Thickness

DZR-S Dicing Blade

The DZR-S dicing blade is composed of metallic nickel and diamond abrasives, featuring fast heat dissipation, excellent chip removal, and superior cutting performance. It is widely applicable for cutting various hard and brittle materials and semiconductor packaging components, such as PCB substrates and ceramic substrates. The use of selected diamond abrasives provides the blade with excellent cutting capability and extended service life. Advanced manufacturing techniques optimize blade hardness, geometry, and abrasive distribution. The controlled concentration of diamond abrasives and bond hardness effectively reduces burr formation during cutting.



Code Notes

Example: DZR-S N4 H2 10/2056X40X0.1W1D2N16

DZR: Model Name	H: Bond Hardness
S: Type with Chip-Removal Slot	H0: Soft Bond H1: Standard Bond H2: Hard Bond
N: Diamond Abrasive Concentration	10/20: Diamond Grit Size

N1	N2	N3	N4	N5
30	50	70	90	110

Serial Number	8/16	10/20	20/30	30/40
Grit Number	1200#	800#	600#	400#

56: Outer Diameter 40: Inner Diameter 0.1: Thickness W: Slot Width D: Slot Depth N: Number of Slots

DZY Dicing Blade

The DZY dicing blade adopts a unique process that integrates the blade with an aluminum alloy flange, providing higher precision. It is suitable for grooving and cutting various hard and brittle materials, such as silicon wafers and compound semiconductors like gallium arsenide. Selected diamond abrasives ensure excellent cutting performance and extended service life. Advanced manufacturing technology controls the concentration of diamond abrasives and bond composition, effectively reducing chipping during cutting. The integrated design also makes loading and unloading more convenient.



Code Notes

Example: DZY-N1-H1-CBA

DZY: Model Name	H: Bond Hardness
N: Diamond Abrasive Concentration	H0: Ultra-Soft Bond H1: Soft Bond H2: Standard Bond H3: Hard Bond

N: Diamond Abrasive Concentration

Serial Number	N0	N1	N2	N3
Concentration	50	70	90	130

C: Diamond Grit Size

Serial Number	A	B	C	D	E	F
Grit Number	4800#	4500#	4000#	3500#	2000#	1700#

B: Blade Edge Length

Serial Number	Z	A	B	C	D	E	F	G	H
Edge Length (mm)	0.25-0.38	0.39-0.51	0.52-0.64	0.65-0.76	0.77-0.89	0.90-1.0	1.0-1.1	1.1-1.2	1.2-1.3

A: Kerf Width Value

Serial Number	Z	A	B	C	D	E	F
KERF (UM)	10-15	16-20	21-25	26-30	31-35	36-40	40-50



METAL BLADE SERIES

JS Metal Blade Series



Metal Bond Cutting

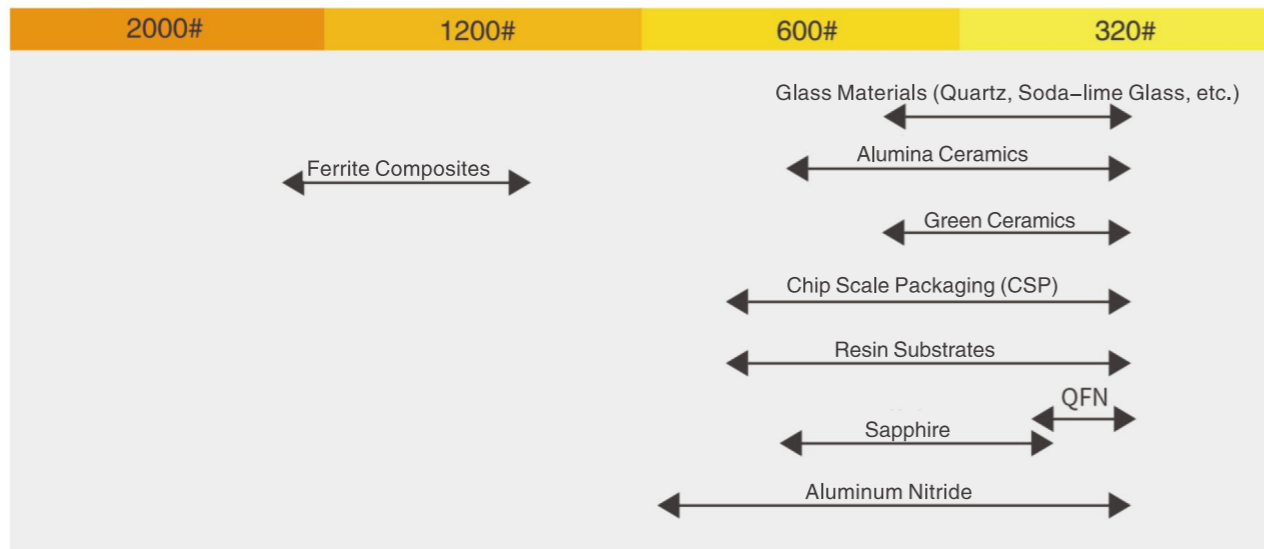
The bond of this product is formulated by blending various metal powders in specific proportions, featuring high precision, high rigidity, high strength, and excellent resistance to breakage. With a wide variety of bond types, it is suitable for cutting different types of products across various applications.



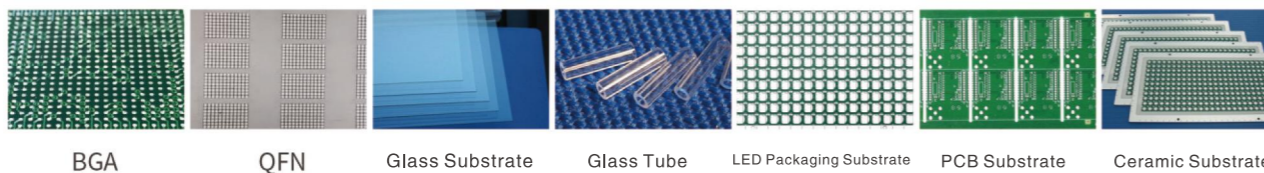
Technical Specifications

SD 800 N70 M60 -C		54×0.15×40 × 45°							
Abrasive Types	Grit Size	Concentration	Bond ^{※3}	Shape	Outer Diameter	Thickness	Inner Diameter	Blade Edge Angle	
SD Synthetic Diamond	180 #180	15 Low	30 Soft	C-Continuous (No Slot)	50	0.1	40	θ	
SDC Coated Synthetic Diamond	230 #230			~	~	Tolerance			
	320 #320	125High	100Hard	S-Open U-Shaped Slot	100	1.2	±0.02	θ	
	400 #400			±0.003	~				
	600 #600					V-V-Angled Type	±0.02	0	
	800 #800								
	1000 #1000								

Application Examples of Different Grit Sizes



Processing Targets



Standard Application Range

Blade Thickness \ Grit Size	0.10-0.15	0.15-0.20	0.20-0.25	0.25-0.35	0.35-1.20
#1000	●	●	●	●	●
#800	●	●	●	●	●
#600	●	●	●	●	●
#400		●	●	●	●
#320			●	●	●
#230				●	●
#180					●

Grit Size

#1000	08-16
#800	10-20
#600	20-30
#400	40-60
#320	325/400
#230	230/270
#180	170/200

RESIN BLADE SERIES

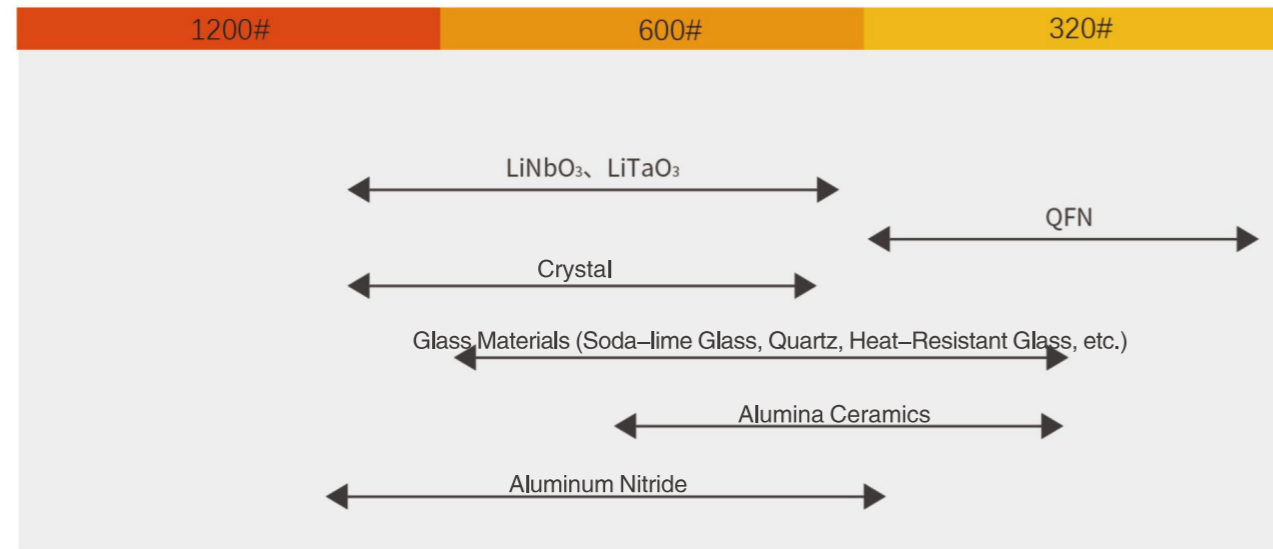
SZ Resin Blade Series

Resin Bond Cutting

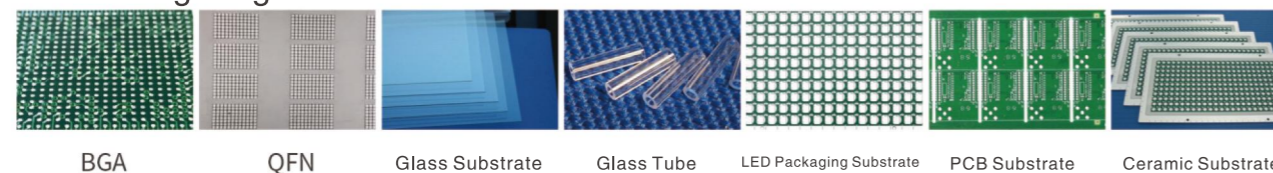
This cutting wheel is an ultra-precision dicing blade made by sintering heat-resistant resin powder, auxiliary additives, and diamond abrasives. It is suitable for cutting semiconductor materials, ceramic materials, as well as glass, crystal, quartz, and related materials.



Application Examples of Different Grit Sizes



Processing Targets



Technical Specifications

SD 800 N70 M60 -C		54×0.15×40					
Abrasive Types	Grit Size	Concentration	Bond ^{*3}	Shape	Outer Diameter	Thickness	Inner Diameter
SD Synthetic Diamond	180 #180	15 Low	30 Soft	C-Continuous (No Slot)	50	0.1	40
SDC Coated Synthetic Diamond	230 #230				~	~	Tolerance
	320 #320	125 High	100 Hard	S-Open U-Shaped Slot	100	1.2	±
	400 #400				±	0.02	~
	600 #600				±	0.003	~
	800 #800				±	0.02	0
	1000 #1000						

Standard Application Range

Grit Size	Blade Thickness				
	0.10-0.15	0.15-0.20	0.20-0.25	0.25-0.35	0.35-1.20
#1000	●	●	●	●	●
#800	●	●	●	●	●
#600	●	●	●	●	●
#400		●	●	●	●
#320			●	●	●
#230				●	●
#180					●

Grit Size

#1000	08-16
#800	10-20
#600	20-30
#400	40-60
#320	325-400
#230	230-270
#180	170-200

FOR SEMICONDUCTOR INDUSTRY UV DICING TAPE



A

Application Fields of Series A Products

Substrate PCB (BGA/QFN), Glass

B

Application Fields of Series B Products

Wafers, MEMS, Glass

C

Application Fields of Series C Products

Ceramic, Glass, Crystal

V

Application Fields of Series V Products

Wafer Dicing, De-taping, Expandable Tape

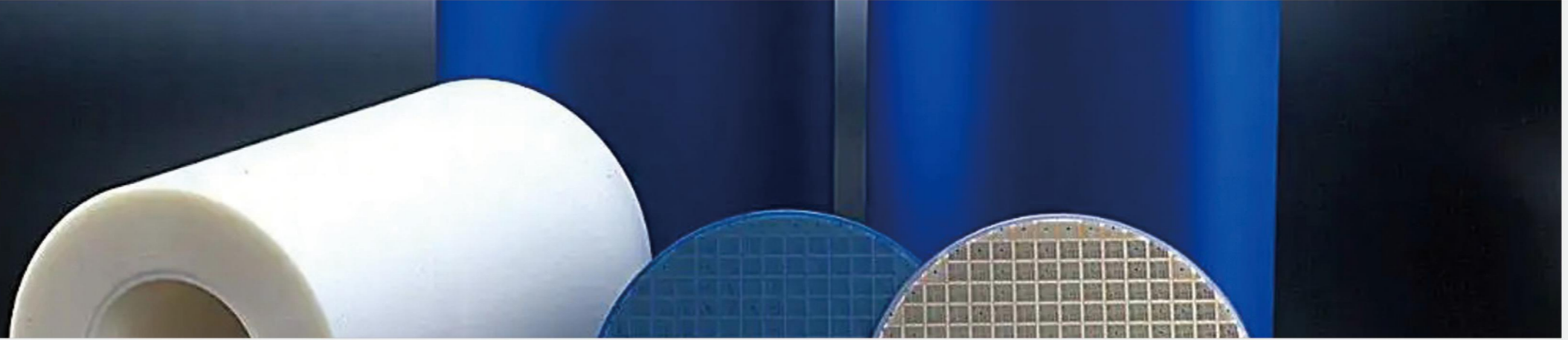
N

Application Fields of Series N Products

Non-UV Products, Blue Tape, etc.

PRODUCT CLASSIFICATION

UV Tape Product Classification



Detailed Applications for Substrate-Type Products

Model	Base Material	Total Thickness	Adhesive Thickness	180° Peel Strength (After UV)	90° Peel Strength (After UV)	Recommended Workpiece	Remarks
A15010-32	PO(150μm)	160	10	9.78 (0.15)	2.42 (0.03)	Substrate PCB / Glass	General Purpose / High Adhesion
A15010-12C	PO(150μm)	160	10	16.6 (0.1)	2.63 (0.04)	High Adhesion	
A15015-62H	PO(150μm)	165	15	17.3 (0.06)	2.9 (0.05)	Substrate PCB / Glass	No Burrs or Residue in Deep Cuts of Small-Sized Workpieces
A15020-11	PO(150μm)	170	20	14.9 (0.26)	4.33 (0.06)	Substrate PCB / Glass	Prevents Chipping or Flaking
A15020-12C	PO(150μm)	170	20	21.8 (0.11)	3.38 (0.04)	Substrate PCB / Glass	
A15010-17B	PO(150μm)	160	10	18.3 (0.4)	4.32 (0.1)	LED	No Material Dispersion After UV Exposure

Detailed Applications for Wafer-Type Products

Model	Base Material	Total Thickness	Adhesive Thickness	180° Peel Strength (After UV)	90° Peel Strength (After UV)	Recommended Workpiece	Remarks
B09010-11	PO(90μm)	100	10	8.3 (0.26)	2.21 (0.04)	Wafer	Reduced Backside Chipping
B09010-22A	PO(90μm)	100	10	6.11 (0.08)	2.16 (0.03)	Wafer	Reduced Backside Chipping
B09010-22D	PO(90μm)	100	10	3.9 (0.08)	1.96 (0.04)	Wafer/MEMS/Glass	Easy to Peel
B08005-22	PO(80μm)	85	5	6.2 (0.11)	1.72 (0.03)	Wafer	Easy to Peel
V08010B-26	PVC(80μm)	90	10	3.4 (0.08)	1.57 (0.04)	Wafer, Silicon, Grinding	Expandable Film

Detailed Applications for PET-Type Products

Model	Base Material	Total Thickness	Adhesive Thickness	180° Peel Strength (After UV)	90° Peel Strength (After UV)	Recommended Workpiece	Remarks
C10020-11	PET(100μm)	120	20	11.6 (0.01)	2.51 (0.03)	Ceramic / Glass / Crystal	Non-Expandable
C10020-22C	PET(100μm)	120	20	14.8 (0.01)	2.61 (0.03)	Ceramic / Glass / Crystal	Non-Expandable

Detailed Applications for Anti-Static Products

Model	Base Material	Total Thickness	Adhesive Thickness	180° Peel Strength (After UV)	90° Peel Strength (After UV)	Recommended Workpiece	Remarks
A15010-1E2D	PO(150μm)	160	10	16.1 (0.04)	2.40 (0.03)	8.5 x 10 (Surface Resistivity)	Anti-Static Adhesive Surface
A15015-1E2D	PO(150μm)	165	15	17.3 (0.05)	2.9 (0.03)	8.5 x 10 (Surface Resistivity)	Anti-Static Adhesive Surface
A15020-1E2D	PO(150μm)	170	20	23.6 (0.05)	4.23 (0.03)	8.5 x 10 (Surface Resistivity)	Anti-Static Adhesive Surface
B09010-2E2D	PO(90μm)	100	10	7.2 (0.1)	2.71 (0.03)	8.5 x 10 (Surface Resistivity)	Anti-Static Adhesive Surface
V08010B-2E6	PVC(80μm)	90	10	3.5 (0.07)	1.59 (0.07)	8.5 x 10 (Wafer)	Anti-Static Adhesive Surface

TEST METHOD: GB2792-2014

●Adhesion: Measured at 20 min after applying and pressing tape to each adherent using a 2 kg roller rolled back and forth three times.

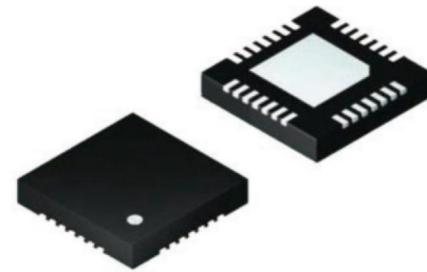
180° peel, pulling speed: 300 mm/min

●UV irradiation: High pressure mercury vapor lamp used. Irradiation was approximately 300 mJ/cm². (Intensity: approximately 75 mW/cm² x approximately 4 seconds at 365 nm)

PRODUCT APPLICATION

Package Dicing

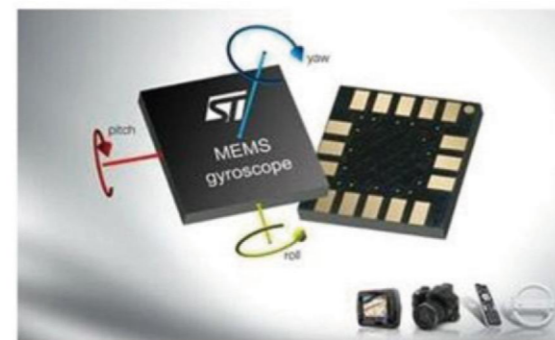
Product Models: A15010-12C, A15010-32, A15020-12C
 Application Process: Post-packaging dicing for traditional packages such as QFN, DFN, BGA
 Processing Material: Epoxy Resin
 (Minimum Chip Size: 0.6 × 0.3mm)



Model	Base Material	Total Thickness	180° Peel Strength (After UV)
A15010-32	PO(150μm)	160	9.78 (0.04)
A15010-12C	PO(150μm)	160	15.6 (0.04)
A15015-62H	PO(150μm)	165	18.6 (0.04)
A15020-12C	PO(150μm)	170	20.3 (0.05)

MEMS Product Dicing

Product Models: A15020-12C, A15010-12C
 Application Process: Post-packaging dicing for MEMS
 Processing Material: Epoxy Resin

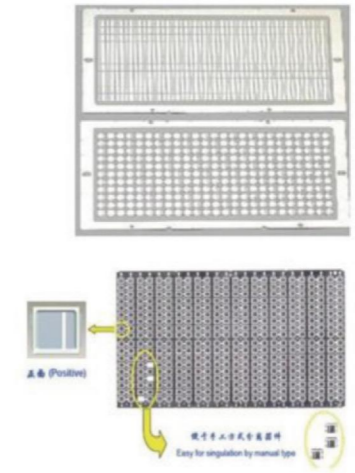


Model	Base Material	Total Thickness	180° Peel Strength (After UV)
A15010-12C	PO(150μm)	170	15.6 (0.04)
A15020-12C	PO(150μm)	160	20.3 (0.05)

LED Product Dicing

Product Models: A15020-32A, A15010-32
 Application Process: Dicing or singulation after SMD and CSP packaging
 Processing Materials: EMC substrate, silicone, etc.

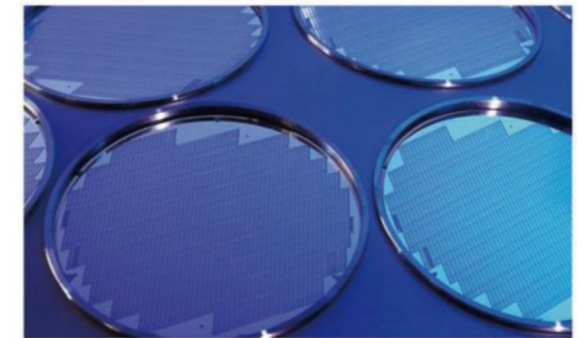
Model	Base Material	Total Thickness	180° Peel Strength (After UV)
A15010-32	PO(150μm)	160	9.78 (0.04)
A15020-12C	PO(150μm)	170	18.7 (0.05)



WAFER Dicing

Product Models: V07010-12M, B09010-22D, B08005-22
 Application Process: Wafer Dicing
 Processing Material: WAFER

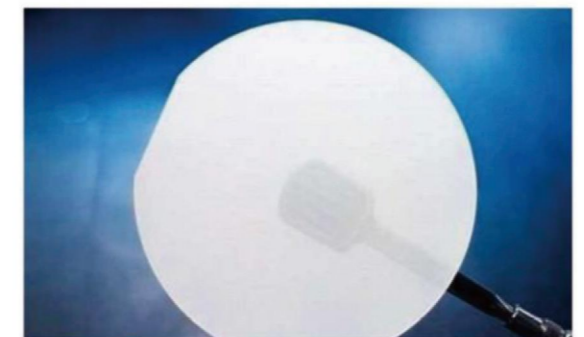
Model	Base Material	Total Thickness	180° Peel Strength (After UV)
V07010-12M	PVC(150μm)	80	3.52 (0.04)
B09010-22D	PO(90μm)	100	4.93 (0.04)
B08005-22	PO(80μm)	85	7.73 (0.06)



WAFER Dicing

Product Model: B09010-2E2A
 Application Process: Wafer Dicing
 Processing Material

Model	Base Material	Total Thickness	180° Peel Strength (After UV)	Anti-Static
B09010-2E2A	PO(90μm)	100	8.083 (0.06)	Anti-static adhesive surface with resistance up to 10 ⁹



DRESSING BOARD

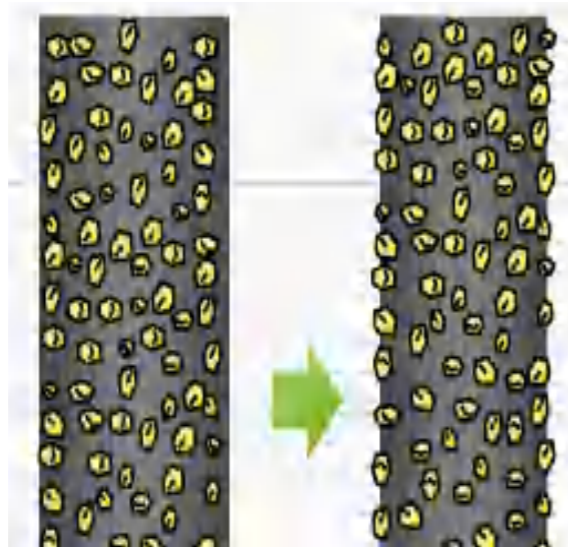
Resin Dressing Board

The dressing board is used for truing and sharpening diamond blades. It removes the bonding material from the blade surface, enhancing cutting performance and optimizing concentricity between the blade and the spindle.



- ★ Maintains stable cutting quality and blade performance.
- ★ Proper dressing under optimal conditions maximizes the blade's cutting capability.

※ Usage Effect



Before Dressing

After Dressing

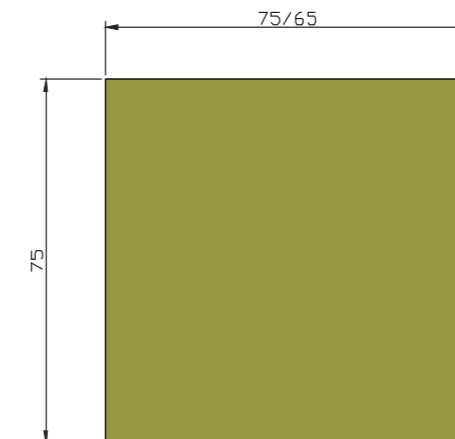
- ★ Dressing board models can be matched according to different blade types.
- ★ Blade dressing methods and process parameters can be provided.

※ Specifications

Grit Size	Thickness (mm)			Available Abrasive Types			
	1	2	3	DZY	DZR	JS	SZ
240#	●	●	●		325-400		140-230
400#	●	●	●		400-600	325-400	270-325
600#	●	●	●		500-700	400-800	400-500
800#	●	●	●		700-1000	600-1000	600-700
1000#	●	●	●		800-1000	800-1300	800-1000
2000#	●	●	●	1700-2000	1200-1300	1000-2000	
3000#	●	●	●	3000	2000-		
4000#	●	●	●	3500-4000			

*Custom sizes available

※ Dimensions





DRESSING BOARD

Metal Dressing Board

The metal dressing board is used for truing metal bond diamond blades. It restores the worn blade edge to achieve optimal cutting performance.



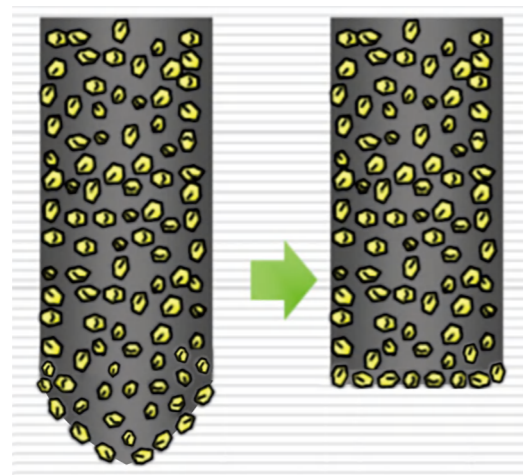
- ★ Maintains stable cutting quality and blade performance.
- ★ Proper dressing under optimal conditions maximizes the blade's cutting capability.

※Specifications

Grit Size	Thickness (mm)			Available Abrasive Types
	1	2	3	JS
280#-1000#	●			280#-1000#

*Custom sizes available

※Usage Effect

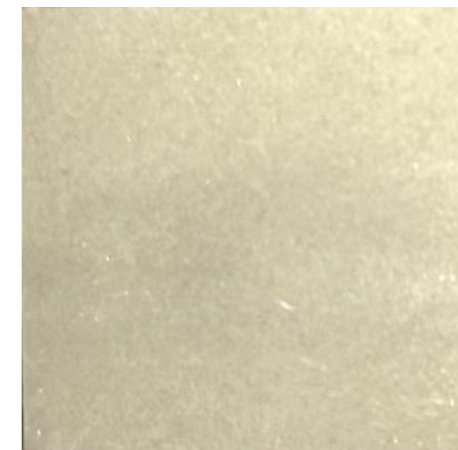


Before Dressing

After Dressing

- ★ Dressing board models can be matched according to different blade types.
- ★ Blade dressing methods and process parameters can be provided.

※Dimensions



Dimensions 30 × 30 mm

Resin Grinding Wheel

树脂磨轮

Adopt the new type resin powder as the bonder, realize the high efficiency and high quality grinding machining to the silicon wafer, glass foundation plate and other materials. Able to greatly improve the smooth degree of the machining surface, needn't trim during machining, realize the stably continuous machining.

Application: flat thinning machining of silicon wafer, glass foundation materials and other hard and fragile materials.

Characteristics:

1. High machining quality;
2. Better sharp degree, needn't trim during machining;
3. Able to provide rough, middle and fine grinding applied grinding wheel according to the operating requirements.



Technical specification:

ML-B-SD2000-BJ01-100 203Dx3Wx7Tx28S

ML	B	SD	2000	BJ01	100	203D	3W	7T	28S
	Anchoring agent type	Grinding pellet type	Pellet size	Anchoring agent	Concentration	Grinding wheel diameter	Grinding wheel gear width	Grinding wheel gear height	Grinding wheel gear quantity
	metal anchoring agent	artificial diamond	320#						
	resin anchoring agent	plated diamond	600#						
	ceramic anchoring agent		800#						
			1200#						
			1500#						
			2000#						
			3000#						
			4000#						

Ceramic Grinding Wheel

陶瓷磨轮

Adopt multiply holes ceramic anchoring agent hold grinding pellets, realize high quality grinding machining to SiC wafer, silicon wafer and other materials. The multiply holes ceramic anchoring agent has excellent bits receive and discharge capacity and water supply capacity of grinding, able to realize the surface roughness which close to polishing.

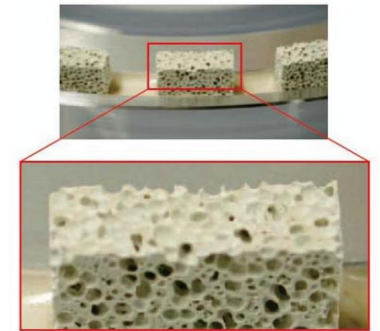
Application: thinning grinding machining of SiC wafer, silicon wafer, chemical compounds semiconductor and other materials.

Characteristics:

1. high machining quality, able to realize the surface roughness which close to polishing;
2. Multiply holes ceramic anchoring agent, able to provide stable grinding capacity;
3. Excellent anti grinding performance, long working life;
4. Rich product types.

Technical specification:

ML-V-SD6000-VK01-100 203Dx3Wx7Tx28S



ML	V	SD	6000	VK01	100	203D	3W	7T	28S
	Anchoring agent type	Grinding pellet type	颗粒大小	Anchoring agent	Concentration	Grinding wheel diameter	Grinding wheel gear width	Grinding wheel gear height	Grinding wheel gear quantity
	metal anchoring agent	artificial diamond	2000#						
	resin anchoring agent	plated diamond	3000#						
	ceramic anchoring agent		4000#						
			6000#						
			8000#						
			10000#						
			12000#						
			15000#						

Silver Paste

导电银浆

Sliver paste is the compound type functional materials which make silver powder as electric conduct filling materials, make the resin, dissolvant and assistant (such as dispersant, stabilizer) as carrier. The main functions are that construct electric conduct layer or graphic electric circuit in the electric elements and the electric conduct circuit. Based on the excellent electric conduct performance and stability, the silver paste already come to be the core foundation materials in the modern electrical manufacture and micro electrical sealing industry.

High temperature silver paste—automobile demist series

Model	Applied areas
Electric conduct silver paste TJ-0880	The produced products which mainly aim to the glass silver paste of automobile behind window. Generally assorting use with model TJ-0665 type silver paste.
Electric conduct silver paste TJ-0665	The produced products which mainly aim to the glass silver paste of automobile behind window. Generally assorting use with model TJ-0880 type silver paste.
Electric conduct silver paste TJ-0680	The produced products which mainly aim to the glass silver paste of automobile mezzanine
Electric conduct silver paste TJ-TP	Laser etching of fine circuit on the electric capacity touch screen applied ITO/PET film foundation material.



High temperature silver paste—GPS, PTC voltage sensitive ceramic series

Model	Applied areas
Electric conduct silver paste TJ-5670	The researched and developed product which mainly aim to PTC, voltage sensitive ceramic foundation materials.
Electric conduct silver paste TJ-5680	The researched and developed product which mainly aim to GPS ceramic antenna foundation materials.

Low temperature silver paste—big and small keyboard series

Model	Applied areas
Electric conduct silver paste TJ-6600	The researched and developed product which specially researched and developed to the notebook keyboard circuit, the same, applicable to the other high-end soft printing electric circuit.
Electric conduct silver paste TJ-5600	Big keyboard circuit, thin film switch, ultra thin soft printing electric circuit.

Other series electric conduct silver paste

Model	Applied areas
Cold light sheet electric conduct silver paste TJ-5600ELC	Widely applied in EL backlight source.
Automobile rear-view mirror/seat heating electric conduct silver paste TJ-3300H	One researched and developed product which mainly aim to automobile rear-view mirror/seat heating film, able to be commonly applied in FFC, soft printing electric circuit.
Mobile phone shield electric conduct silver paste TJ-1200B	Soft printing electric circuits of mobile phone antenna, IC radio frequency card, thin film switch and others.
Electric conduct glue TJ-D5606	Electric conduct performance connection, keyboard LED gluing, printing circuit and others of the electric elements.
Electromagnetism shield silver—copper paste TJ-5600T	One researched and developed product which mainly aim to shield electric circuit and cold light sheet, able to be widely applied in soft printing electric circuit.
Thin film switch electric conduct silver paste TJ-1200	Able to be widely applied in thin film switch and other soft printing electric circuit;

Glass Powder

玻璃粉

WT series glass powder is the high performance lead series glass deactivation material which specially researched and developed for various types chips deactivation protection. This product based on classic yellow lead, monox and alumina (PbO—SiO₂—AL₂O₃) system, through innovation components design and fine technology control, completely developed the advantages of glass with lead at low temperature flowability, wettability and high insulation performance under the premise that guarantee perfectly thermal match with silicon base chips. We make the system production and operating management scheme to make ensure that, according to the globe environment protection laws, regulations and safety standards at the same time of make ensure the product meeting the highest performance requirements, aim to provide the deactivation protection material selection to the customers which compatible excellent performance, high reliability and completely according to the standards.

Product

Product name: lead—silicon—aluminum glass powder (Pb—Si—Al series glass powder)
Lead—Silicon—Aluminum Glass Powder(Pb—Si—Al Glass Powder)
[WT-230] Product number: [WT-230]
Appearance and properties: white powder, no stink, no smell, even pellets, better flowability.
Main components (mass percentage): yellow lead(PbO),silica (SiO₂), alumina(AL₂O₃)



Technical Specifications

Parameters	WT-200S	WT-230S
Average pellet diameter (D50)	5.2 μm	5.6 μm
Density	3.82g/cm ³	3.56g/cm ³
Soften temperature(Ts)	780°C	830°C
Vitrification shift temperature (Tg)	595°C	610°C
Thermal expansion coefficient (25–720°C)	44 × 10 ⁻⁷ /°C	41 × 10 ⁻⁷ /°C
Water content	≤0.1%	≤0.1%
Purity	≥99.99%	≥99.99%
Volume electric resistance ratio	≥ 1 × 10 ¹⁴ Ω · cm	≥ 1 × 10 ¹⁴ Ω · cm

Note: we support your detail deactivation protection structure (such as chip size, foundation plate materials) and application technology, process customized adjustment to the key parameters such as CTE, Tg, Ts and others.

Product Description and Core Advantages

1. Ripe system, excellent performance

WT series glass powder developing based on classic system of PbO—SiO₂—AL₂O₃. This product has excellent low temperature melt characteristics and wide burning technology window, make the glass paste able to completely flowing and densifying under oppositely lower temperature. At the same time, make the glass has excellent wettability and interface combine force to the silicon, ceramic and multiply metal frames, this is most important to form firm and non defects deactivation protection structures.

2. Accurate thermal matching, rooting remove the buckling risk

We realize the accurate control capacity of the revolutionary thermal expansion coefficient (CTE) in this ripe system through special recipe adjustment and control technology. Product CTE able to be stably controlled within narrow range 3.6–4.5 × 10⁻⁶ /°C. Realize “Thermal compatibility” from the material source, root remove the deactivation protection body buckling, cracks and other reliability solid problems which caused by that CET loss matching, especially suitable to the deactivation technology of big size and high power chips.

3. Reliable electrical protection, deactivation and insulation which has excellent technology tolerant degree: burning formed glass layer compact without holes, it has ultra high volume electric resistance ratio (>10¹⁴ Ω · cm) and excellent damp proof and anti ion transmit performance, provide durable physic isolation and chemical protection to the chips. Excellent technology adaptability: the product has the optimized soften point and flowing deformation characteristics, better compatibility with various organic carriers, perfectly adapt to screen grid printing, shaving, coating, light resistance and other main technology, provide the high degree flexibility and latitude to the customer production.